

## Power Electronics

Prof. B.G. Fernandes

Department of Electrical Engineering

Indian Institute of Technology, Bombay

### Lecture - 7

Hello, in my last class we discussed about SCRs. It is a semi control switch. Why it is a semi control switch? Because, device can be turned on by applying a control signal at the gate but then you cannot turn it off by applying a control signal at the gate. It is a latching device. Why it is a latching device? Control signal at the gate can be withdrawn, once the current through the device is higher than the latching. It does not require a continuous gate drive. It allows conduction only when it is forward biased and it is in conduction mode. So, another device that we studied in the previous lecture was a track, functionally it is equivalent to 2 thyristors connected anti parallel. So, it is like this.

(Refer Slide Time: 2:07)

**Review :**  
TRIAC :-> Functionally equivalent to 2 thyristors connected anti-parallel.  
Can be triggered by

$MT_2 +ve$		W.R.T. $MT_1$
$I_G +ve$		
$MT_2 -ve$		W.R.T. $MT_1$
$I_G -ve$		

$\Rightarrow \frac{dv}{dt}$  rating < than that of SCR

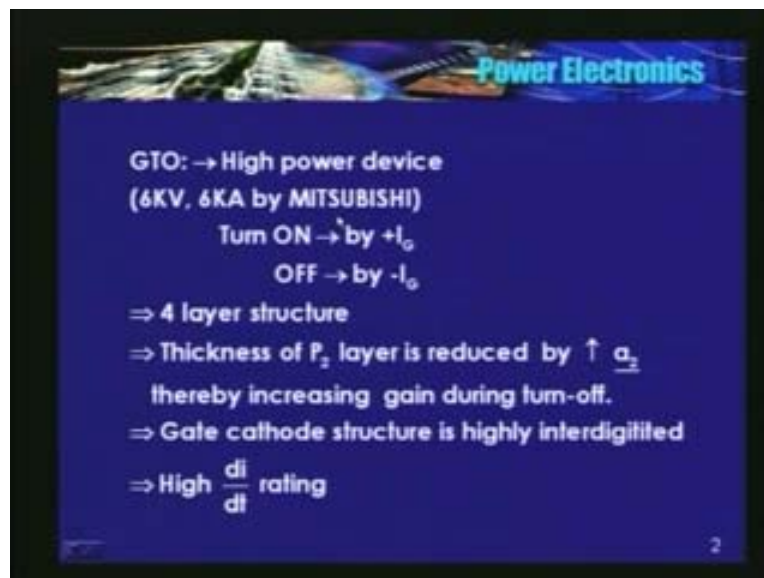
There are 2 thyristors connected anti parallel and a common gate; functionally is equivalent. I told you that this device can be triggered by making  $MT_2$  positive with respect to  $MT_1$  and supplying a positive gate current with respect to  $MT_1$ . This condition, both positive,  $MT_2$  is positive,  $I_G$  is positive with respect to  $MT_1$ , it can also be triggered by making  $MT_2$  negative,  $I_G$  negative with respect to  $MT_1$ . So, the VI characteristics, they look like this, positive  $I_G$  and a negative  $I_G$ . So, what is the difference between the SCR and a TRIAC? The  $dv$  by  $dt$  rating for

track is less compared to that of a SCR. TRIAC has a less time to recover the blocking mode compared to a SCR. Why?

See in this circuit, ((Refer Slide Time: 3:42)) at any given time if this device is reverse biased, this gets forward biased. When this device is turning off, a negative voltage gets applied across it and this negative voltage forward biases this device and in case the rate of change of voltage is high, this device may turn on. So, these are some of the essential difference between a track and a SCR.

The next device that we studied was a GTO, it is again a high power device, a 6 KV, 6 kilo ampere device is available, is being manufactured by Mitsubishi. See here, 6 KV, 6 kilo amperes by Mitsubishi, it has being developed.

(Refer Slide Time: 4:52)



SCR and track, these are semi controlled switches, both, whereas, GTO is a fully controlled switch. You can turn on by positive  $I_G$  and you can turn off by negative  $I_G$ . GTO has 4 layer structures similar to SCR. What are the differences? I told you that thickness of  $P_2$  layer is reduced in order to increase  $\alpha_2$ , thereby, increase in the gain during turn off.

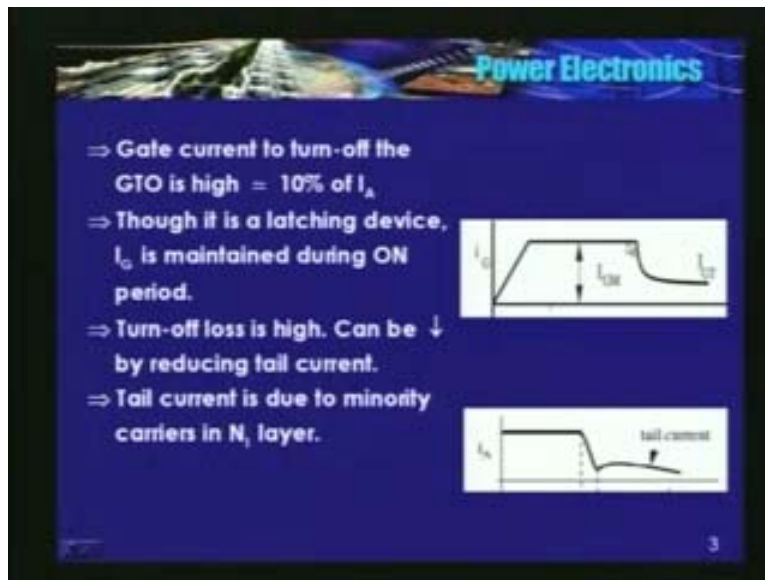
See, turn off gain is a function of  $\alpha_2$ . It is  $\alpha_2$  divided by  $\alpha_1 + \alpha_2 - 1$ . Now, the gain can be increased by increasing  $\alpha_2$ . How do I increase  $\alpha_2$ ? By decreasing the thickness of  $P_2$  that is why I told you in my last lecture. What is another essential difference between GTO and a track or GTO and a SCR?

In GTO, gate and cathode structures are highly inter digitated. It is something like this, highly inter digitated. So, the result is cathode periphery has increased and even the remote part of the

cathode is very near to the gate. That is what I told you, a high power GTO can be seen as a large number of small GTOs in parallel. So therefore, it has a very high di by dt rating. Because, of the highly gate cathode structure being highly inter digitated, a large area is available during conduction or at the instant of turn on, a large area is available.

So therefore, it has a very high di by dt rating. In other words, GTO can be brought into conduction at a much faster rate or a turn on snubber, a small inductor is required in series with the device compared to SCR. What is another feature that has to be taken into account while turn on? A gate current, a continuous gate current should be maintained in the on period. See, it is something like this.

(Refer Slide Time: 8:06)



Having turned on the device completely, the gate current can be reduced but a small current should be maintained continuously because I told you, momentarily if  $I_A$  falls or the anode current falls, some of the cathode highlands may turn off and subsequently if the anode current increases, the entire area is not available for conduction. So, it may so happen that only a small area that is available, current is the same, so there will be a hot spots and device may fail.

Remember, though GTO can be turned off by applying a control signal at the gate, the turn off gain is small. So, a large current is required to turn off a conducting GTO. Turn off loss is also high. Why? It is because of the tail current. How do you reduce the turn off loss? Turn off loss can be reduced by reducing the duration for which the tail current falls.

We have seen, in the sense when the GTO is turning off, voltage across that is increasing but for substantial period tail current flows through the device. Therefore, turn off losses is high. See, like this, tail current, a very high dr by dt and this is a tail current period and during this period,

voltage across a device, as a result to quite a high value, there will be, turn off losses will be high. How will you reduce this tail current or what is a reason for this tail current? It is due to the minority carriers in  $N_1$  layer.

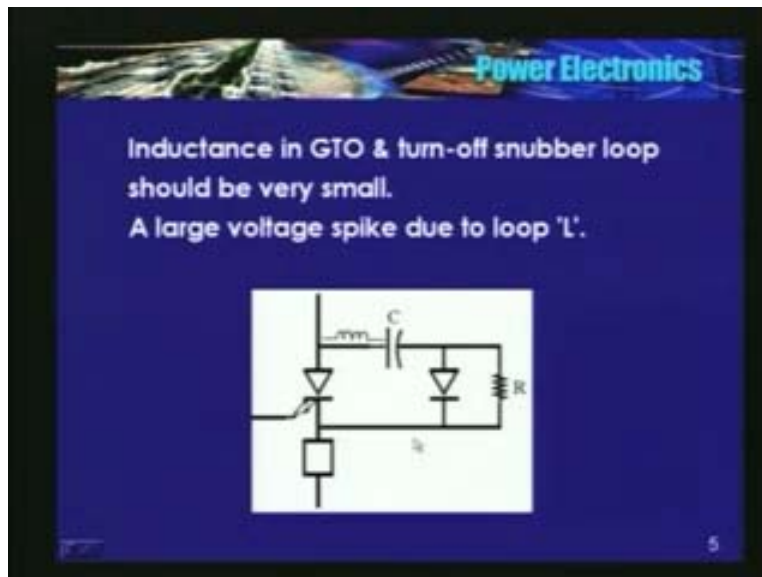
(Refer Slide Time: 10:37)

⇒ Duration of tail current  $\uparrow$   
with thickness of  $N_1$  layer  
⇒ This duration can be  $\downarrow$  by  
using anode short structure  
At regular intervals  $N^-$  region  
penetrates  $P_1$  layer to make  
contact with  $N^-$  region.  
⇒ Cannot block -ve  $V$

So, the duration of tail current can be reduced by penetrating this, a highly doped N layer in the P layer. See, we see N layer is penetrating at regular intervals in the P layer and it is directly in contact with N minus layer and because of this the tail current or the duration for which the tail current flows reduces. But then, this structure cannot block a negative voltage. This is also known as an anode short structure. Now, whereas this can block a negative voltage because of junction  $J_1$ , whereas here, junction  $J_1$  or N plus is directly in contact with N minus junction  $J_1$ . So, it cannot block negative voltage, whereas this device can block a negative voltage.

What is another point that we discussed? The inductance in the loop found by GTO and the turn off snubber should be very small, see this.

(Refer Slide Time: 12:15)



The loop inductance should be very small. Why? It is because of this loop inductance when you turn off GTO, the current does not get transferred to this snubber. So, there is going to be a large voltage spike. So, this inductance should be very small. In other words, snubber layout is very, I will show you a GTO manufactured by Toshiba.

(Refer Slide Time: 12:53)



A 600 ampere device, gate terminal and we need to use 2 heat sinks. It is like, formed sandwiched in between 2 heat sinks, a 600 ampere GTO. So, that is about the GTO. So, we have studied SCR, track and GTO.

Fourth one, a BJT, bipolar junction transistor, I told you that it was developed in 1948 and in 1975 a 300 volt, 400 ampere giant transistor was developed by Toshiba. See here, in 1975 a 300 volt 400 ampere giant transistor by Toshiba.

(Refer Slide Time: 14:03)

Power transistors are normally of NPN type and the N layer which forms the collector is the thickest one, because that layer, the N layer has to block the voltage. Can you block the reverse voltage? Base emitter or emitter junction is highly doped, so therefore, the breakdown voltage or base emitter junction is very small. Therefore, reverse blocking capability is small. Invariably, BJT in power electronic circuits are operated either in saturation not deep in saturation, just at the edge of the saturation and in cut off. Definitely, not inactive because in active power loss that is taking place the device is high.

Generally, for high voltage BJT, current gain is low and especially it is operated in saturation. See, in saturation, collector current no longer equal to beta into  $I_B$  where beta is gain when it is operating in active mode. In saturation, how to determine the collector current?  $I_C$  is equal to  $V_{CC}$  minus  $V_C$  is sat divided by  $R_L$ .

See, in this circuit assume that this BJT is operating in saturation.  $I_C$  is  $V_{CC}$  minus,  $V_C$  is sat divided by  $R$  and it is not equal to beta into  $I_B$  where beta is the gain when it is operating in active mode or active reach.

First of all, high voltage BJT is current gain is low and it is operated in saturation. So, as the collector current increases, the base current requirement also increases. So, how do I overcome this limitation? Use a Darlington circuit. What is a Darlington circuit? See, it is shown here.

(Refer Slide Time: 17:01)

⇒ For high voltage BJT, current gain is low when operated in saturation.

⇒ Use Darlington circuit

⇒ Requires a low base current

⇒  $\beta_1$  &  $\beta_2$  are current gains of transistors.

$I_C = I_{C1} + I_{C2}$

$I_C = \beta_1 I_{B1} + \beta_2 I_{B2}$

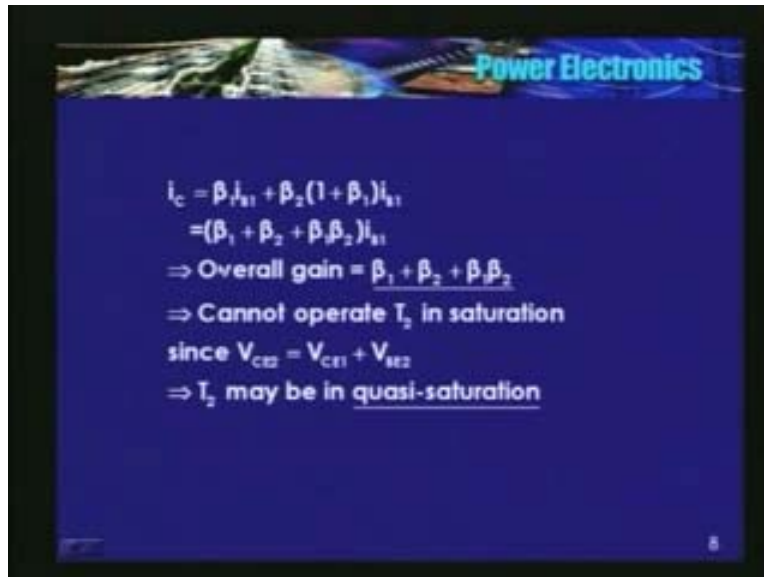
But  $I_{B2} = I_{E1} = (\beta + 1) I_{B1}$

2 transistors or more than 2 connected in this fashion. Now, what is a gain of this combination?  $I_C$  is the total current,  $I_{C1}$  is flowing through transistor 1 and  $I_{C2}$  is flowing through transistor 2.

So, total  $I_C$  is  $I_{C1}$  plus  $I_{C2}$  and what is  $I_{C1}$ ? It is  $\beta_{a1}$  into  $I_{B1}$ . Some  $I_{B1}$  is flowing into the base of transistor 1 and I am measuring some beta. Definitely, is not the same beta of the transistor when it is operating in active mode.

So,  $\beta_{a1}$  into  $I_{B1}$  is  $I_{C1}$ . Similarly,  $I_{C2}$  is some  $\beta_{a2}$  into  $I_{B2}$ . This is the base current,  $I_{B2}$  but then what is  $I_{B2}$ ?  $I_{B2}$  is same as the emitter current of transistor 1,  $I_{E1}$  and what is a relationship between  $I_{E1}$  and  $I_{B1}$ ? It is  $\beta + 1$  into  $I_{B1}$ . Now, you substitute this value in this equation. What do you get?

(Refer Slide Time: 18:50)



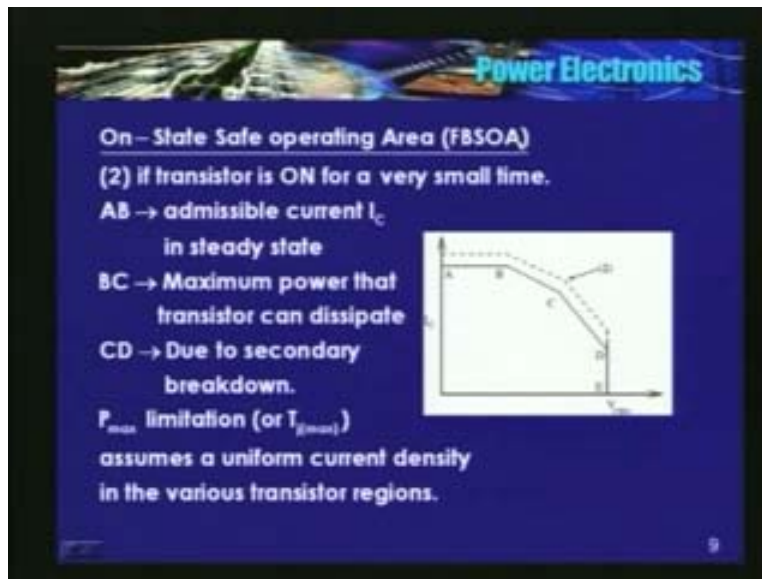
You will get,  $\beta_1 + \beta_2 + \beta_1 \beta_2$  into  $I_{B1}$ . So, the overall gain here is  $\beta_1 + \beta_2 + \beta_1 \beta_2$ . So therefore, for the same  $I_C$ , I require a very small base current that has to be supplied to transistor 1. But then, what is the disadvantage here? Can I operate  $T_2$  in saturation? Answer is no. Why?

See, in this circuit, what is  $V_{CE2}$ ?  $V_{CE2}$  is equal to  $V_{BE2}$  plus  $V_{CE1}$ .  $V_{BE2}$  plus  $V_{CE1}$  is equal to  $V_{E2}$ . I am assuming  $V_{BE2}$  of the order of 0.7 volts, I am assuming and I am assuming that transistor  $T_1$  is in saturation. So,  $V_{CE2}$  equal to  $V_C$  is sat of transistor 1 plus  $V_{BE2}$ .

So therefore, it may not be possible to operate transistor 2 in saturation. So therefore, the loss is taking place in transistor, the final transistor or transistor 2 here, are high. So, that is the disadvantage. Now, how about the safe operating area of the device when it is in forward biased mode or when it is conduction mode? See it is here, on state safe operating area or forward biased safe operating area, FBSOA.



(Refer Slide Time: 21:20)



Maybe, in my second or third lecture while discussing the ideal switch, I said, we drew 3 limits. One is  $I_C$  current that is flowing through the device, voltage through the device, sorry, voltage across the device and another one is a power limit. But, if you see for a BJT, there are 4 limits,  $I_C$  versus  $V_{CE}$ . So, if you see AB, it is an admissible current,  $I_C$  in steady state. So, a device can carry this much of current in the voltage across it is, may be of this value.

Beyond that point, there is another boundary BC. It is the maximum power that the transistor can dissipate and CD is due to secondary breakdown. What do you mean by secondary breakdown? I will explain to you. BC is the maximum power that a device can dissipate. It assumes that a uniform current density in the various transistor regions. So, BC limit assumes that uniform current density throughout.

Let me tell you one thing, it is just not possible to achieve this. Transistor is a minority carrier device. It has a negative resistance coefficient, it is a property. BJT has a negative minority carrier device. Therefore, it has a negative resistance coefficient. So in other words, as the temperature increases, resistance comes down.

(Refer Slide Time: 24:07)

The slide is titled "Power Electronics" and features a blue background with white text. The text is as follows:

- ⇒ Difficult to achieve
- ⇒ BJT is a minority carrier device
- ⇒ Has a -ve resistance coefficient.
- ⇒ Resistance ↓ as temp. ↑
- (∴ Minority carrier density ∝ to intrinsic current density which increases exponentially with temperature)
- ⇒ Power dissipation ↑ as R ↓

To the right of the text is a circuit diagram showing two resistors, labeled  $R_1$  and  $R_2$ , connected in parallel. The number "10" is visible in the bottom right corner of the slide.

See in this, one way to explain or the reason for having a negative resistance coefficient is this, the minority carrier density in the transistor. The minority carrier density is proportional to the intrinsic current density and which increases exponentially with the temperature. Since, it is a, BJT is a minority carrier device, it has a negative resistance coefficient and it is because of this.

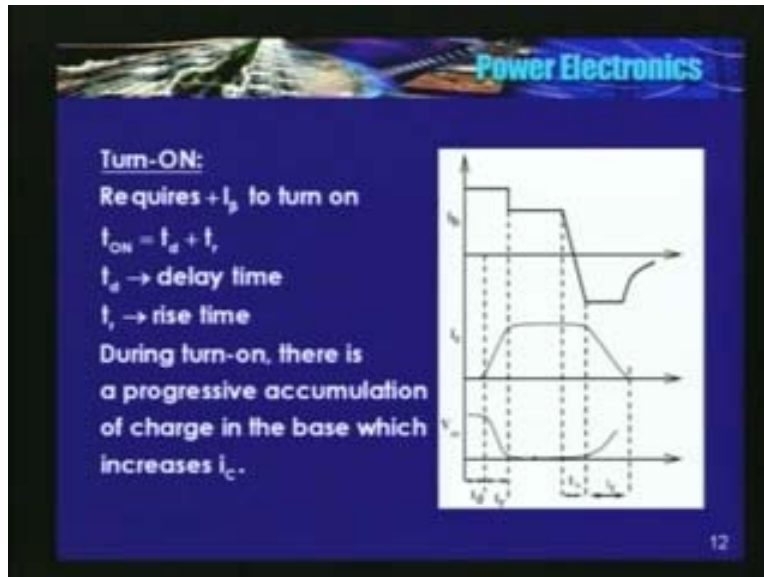
So, since it has negative resistance coefficient, paralleling 2 transistors is difficult. For that matter, any device which has a negative resistance coefficient, paralleling is difficult. Why it is difficult? See, I will just explain to you. I have connected 2 resistors in parallel. Assume that 1 of them has a negative resistance coefficient. Because of the temperature rise,  $R_1$  has decreased by a small value,  $R_1$  minus delta  $R_1$ . So, there is a slight decrease in the resistance. Now, this 2 are in parallel. So, smaller the resistance, higher is the current that it will carry.

So, current that is flowing through  $R_1$  will increase. As the current in the  $R_1$  increases, power dissipated in  $R_1$  increases. Now, the power dissipated in  $R_1$  increases, temperature increases. Now, if temperature increases, again there is a reduction in the resistance because it has negative resistance coefficient. So, there is going to be again a reduction in the total resistance of  $R_1$ . So, thereby, it starts carrying more current. So, it goes on building up and eventually it will fail.

So therefore, any device which has a negative resistance coefficient, paralleling is difficult. So, that is about the secondary breakdown and this is due to the minority carrier device and the last one is a DE. E is the maximum voltage that the device can sustain, DE. This is for a study state or continuous current and in case, if the transistor is on for a very short duration, the boundaries of SOA expand.

See here, this dotted for the device when it is on for very short duration. Because, if a device is on for very short duration, temperature rise or power dissipation limit can also be increased.

(Refer Slide Time: 28:04)



Now, coming to the turn of the BJT, all of us now, it requires a positive  $I_B$  to turn on. So, here are the wave forms. See, in the on period, there are 2 values of  $I_B$ . I will tell you sometimes later the reason for this. A positive  $I_B$  has been applied to the base but then the collector current does not start increasing immediately. It takes some time what is known as the delay time.

During  $t_d$ , though you have applied a positive  $I_B$ ,  $I_C$  is 0 and  $V_{CC}$  is the rated. After  $t_d$ ,  $I_C$  collector current starts increasing and the collector voltage starts falling and this increase in current is determined by the load circuit or the external circuit. So, the total on time is  $t_d$  plus  $t_r$ , the delay time and the rise time. This total  $t_{on}$  time should be as small as possible. So, how do you reduce this  $t_{on}$ ?  $t_{on}$  can be reduced by momentarily supplying a high current at the base.

So, that is the reason, at this point or during this period, during on period, a high current is flowing through the base, into the base. This value is approximately, 1.5 times this value but then why  $I_B$  should be reduced after  $t_{on}$ ? Why cannot you maintain the same  $I_B$ ? If you maintain the same  $I_B$ , transistor may go into, deep into saturation. So, that has to be avoided. Why that has to be avoided? We will study in the turn off process.

So, when the device is turned on, if you see,  $V_{CE}$  has dropped down to a very low value. Of course, definitely not equal to 0. It is  $V_{CE sat}$ , a good power transistor, this value could be of the order of 2volts. So, on state power loss is  $V_{CE sat}$  multiplied by  $I_C$ . It is an on state power loss. So, it is mentioned here.

(Refer Slide Time: 31:39)

Power Electronics

$t_d \rightarrow$  delay time.  
 $t_r \rightarrow$  should be very small  
In order to reduce  $t_{ON}$ , supply  $I_b = 1.5 I_{b(required)}$   
 $\Rightarrow$  Transistor is operated in quasi saturation mode.  
On state loss =  $V_{CE(sat)} * I_C$

13

In order to reduce the  $t_{on}$  period, supply the base current equal to 1.5 times the required or the steady state  $I_B$ .

(Refer Slide Time: 34:55)

Power Electronics

Turn-off:  
 $t = t_s + t_f$   
 $t_s \rightarrow$  Storage time  
= delay between the change of base current & the instant when  $I_c$  starts  $\downarrow$ .  
 $\Rightarrow$  Limits the upper frequency of operation  
 $t_f \rightarrow$  Fall time of  $I_c$   
Storage time: If transistor is in saturation/quasi saturation, width of base region  $\uparrow$   
 $\Rightarrow$  Equivalent to as if a part of collector is transformed to base.  $I_c$  remains constant.

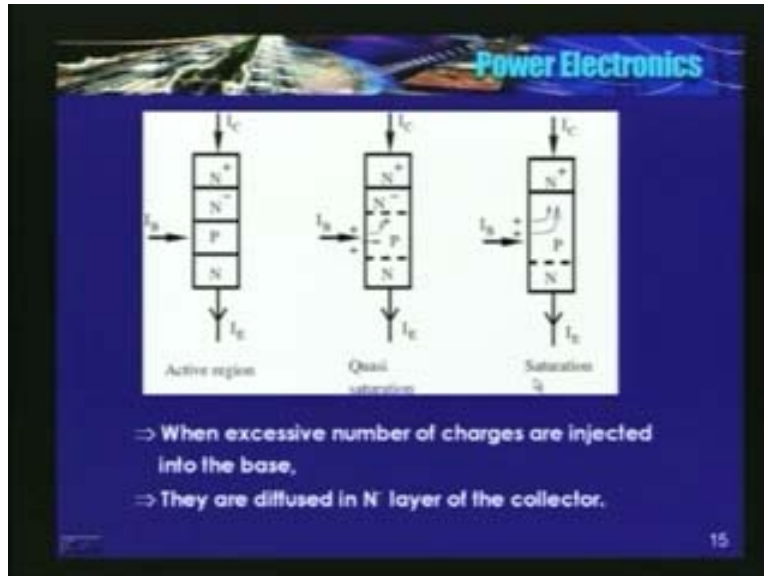
14

Now, coming to turn off, there are or  $t_{off}$  consists of  $t_s$  what is known as storage time plus the fall time of  $I_C$ . Similar to GTO, during storage time, though the gate signal or gate current has become negative,  $I_C$  remains approximately same. So in other words, the  $t_s$ , the storage time is the delay between the change of base current from positive to negative and the instant when  $I_C$

starts reducing, higher the  $t_s$ , higher is the total turn off time. So, as the  $t_{off}$  time increases, you may have to come down on the upper frequency of operation.

So now, let us study the operation of a transistor when it is in saturation. When the transistor is in saturation or in quasi-saturation, the width of the base region increases, say, I just show, you see in this figure.

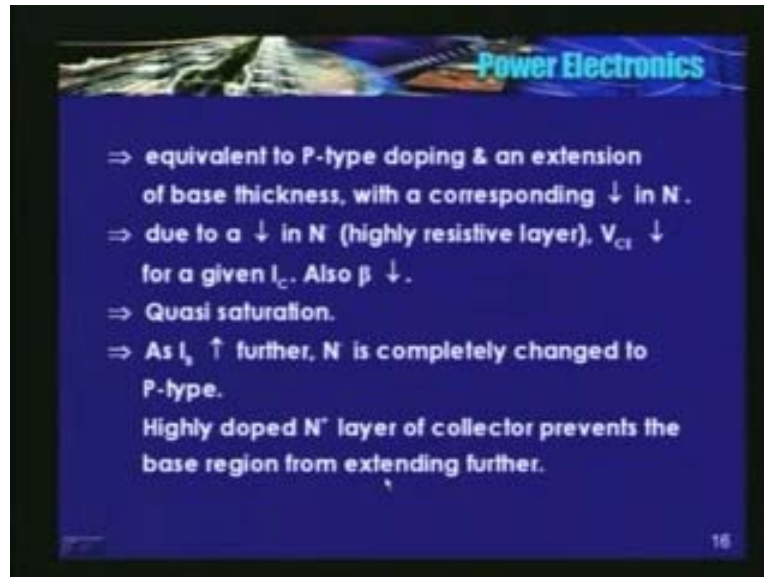
(Refer Slide Time: 33:22)



This is a normal transistor in active region. N P under N layer, this N minus is lightly doped and N plus is highly doped and this thickness will determine the maximum voltage that it can block. So, as  $I_B$  increases, the thickness of N minus layer decreases. See in this figure, this layer decreases because you are injecting a large number of charges into the base and they get diffused into N minus layer. This is a quasi-saturation region.

Now, thickness of N minus layer is reducing. It is a highly resistive layer, the thickness is reducing. Therefore, the voltage drop across the transistor,  $V_{CE}$  also falls. As  $I_B$  is increased further, this N minus layer completely disappears and this region or this mode of operation is known as saturation mode. Devices completely saturated or highly saturated. See, the explanation is given here.

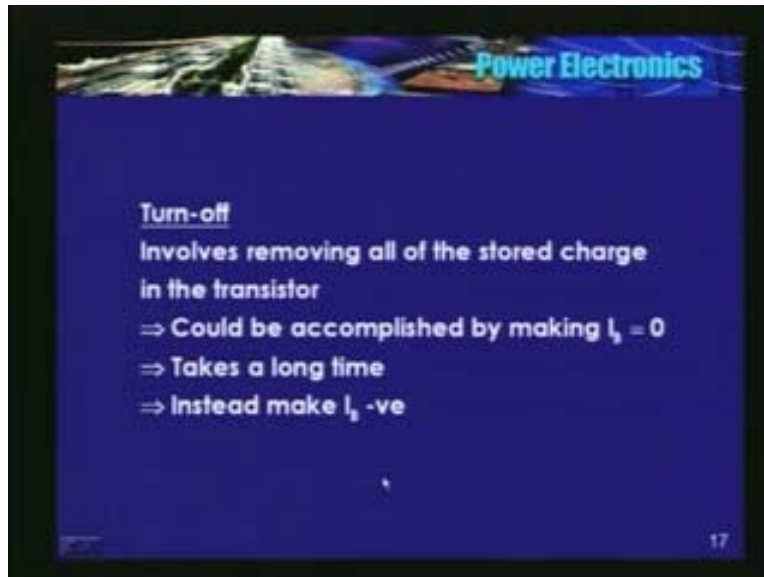
(Refer Slide Time: 35:20)



Saturation is equivalent to the P-type doping and an extension of base thickness with a corresponding decrease in N minus. It is this figure wherein, there is a reduction in the N minus layer. It is equivalent to P-type doping and an extension of base thickness with the corresponding decrease in N minus layer. Now, due to this decrease in N minus, because lightly doped, N minus, minus indicates the doping level is low, is a highly resistive layer.

So,  $V_{CE}$  drops for a given  $I_C$  and this we know, as the transistor saturates, gain comes down and as  $I_B$  is increased further,  $N_1$  is completely changed to P-type and this highly doped N plus layer of the collector prevents the base region from extending further. It cannot, the base region does not extend further.

(Refer Slide Time: 36:54)



So, how do I turn off the transistor? It involves the removing of all the stored charge in the transistor. See, during turn on there is a progressive increase of charges into the base. Now, the turn off is removing all the stored charges from the base or from the transistor. Now, this can be accomplished by making  $I_B$  is equal to 0.

Just open the base terminal  $I_B$  is equal to 0. Transistor will turn off but then it takes a long time. Now instead, you make  $I_B$  negative, a negative base drive. Invariably, a BJT is turned off by applying a negative  $I_B$ .

How much  $I_B$  should be flowing out of the base to turn off the transistor? See, to turn on the transistor, we supplied a high pulse of current to reduce the on time and transistor is operated in all most in the saturation region. In other words, it is just entering the saturation region.

Now, you want to turn it off, what should be the value of  $I_B$ ? Remember, prior to turn off if the transistor is in over saturated region, in other words if the transistor is operating deep into saturation, a large  $I_B$  should not be applied. A high value of minus  $I_B$  should not be applied to turn it off. Why? If you apply a large value of minus  $I_B$  in the base, it will result into the rapid evacuation of carriers from the base.

There is going to be rapid evacuation of the charges from the base. Therefore, the base emitter junction becomes cut off but then holes in the collector region requires certain time to recombine and let me tell you one thing, this  $I_B$  minus  $I_B$  has negligible effect on this time. By supplying a minus  $I_B$ , rapid evacuation of the carriers from the base has taken place, the base emitter junction has becomes cut off now, but then those whole switches are there in the collector region, they require a certain time to recombine and minus  $I_B$  has negligible effect on this time.

So therefore, the times are instant when the base emitter junction has become cut off. Till this process gets completed, this is equivalent to diode in the reverse recovery mode. See here, from the time base emitter junction is in cut off and base collector current continuous to flow that is due to the holes, base collector.

(Refer Slide Time: 40:34)

Power Electronics

- ⇒ From the time B-E junction is in cut-off and base collector current continues to flow, operation is equivalent to a diode during  $t_r$ ,
- ⇒ Also known as current tail
- ⇒ During this period, in most cases  $V_C$  is already high
- ⇒ High losses
- ⇒ Risk of thermal runaway
- ⇒  $I_C$  gradually in the -ve direction

The operation is equivalent to a diode during  $t_{rr}$  or reverse recovery time and this is also known as the current tail. Invariably, during this period,  $V_C$  is already attained a reasonably high value, almost similar to a GTO. We had current tail there because of the minority carriers in N minus.

So, during tail current tail period,  $V_C$  is high. So therefore, losses that are taking place in the device will increase. So, if the losses in the device increase, you could have something known as thermal run away because of the negative resistance coefficient.

So therefore, if the device is operated in saturation,  $I_B$  should be gradually increased in a negative direction, something like this. High value of  $I_B$  to reduce the on time or  $t_{on}$  at study state and it is a gradual increase in the negative direction. A constant value then afterwards current, this is  $I_B$ , gradually decreased in the negative direction. Now, how do you ensure that transistor does not get into saturation?

So, there is trade of, if the transistor gets deep into saturation,  $V_{CE}$  is low. So therefore, total losses that are taking place in the device are low but then as it is driven into saturation, storage time increases. So, you have to come down on the frequency of operation, natural frequency or the switching frequency of the device.



Now, instead of operating the device into deep into saturation, operate somewhere at the edge what is known as the quasi saturation. How will you ensure this? There is a network what is known as the anti saturation network is also known as the Baker clamp which ensures transistor is always operated in quasi saturation. See, here is the network.

(Refer Slide Time: 43:40)

**Power Electronics**

**Anti-Saturation network (Baker clamp)**

Operating the transistor in Quasi saturation region increases  $V_{CE}$  slightly. But  $I_c$  is greatly reduced. Prevent the BJT from over saturating.

Now,  $V_{CE} = V_{BE} + V_{D2} + V_{D3} - V_{D1}$   
 $\Rightarrow V_{CE}$  is maintained at  $V_{BE} + V_{D1}$

By connecting additional diodes in series with  $D_2$  or  $D_3$ ,  $V_{CE}$  can be increased.

20

This is the power BJT and this network  $D_1$   $D_2$   $D_3$   $D_4$ . I will explain to you the function of each diode. See, the advantage of operating the transistor in quasi saturation is that  $V_{CE}$  increases slightly but then the storage time reduces significantly. There is a great reduction in  $t_s$ , the storage time.

Now, with this anti saturation network, what is the value of  $V_{CE}$ ?  $V_{CE}$  gives the measure of the saturation level or degree of saturation of the transistor. See here now  $V_{CE}$ , this voltage is equal to  $V_{BE}$  plus  $V_{D1}$ , sorry  $V_{D2}$  plus  $V_{D3}$ . These 2 diode drops minus this drop.

So,  $V_{BE}$  plus these 2 diodes drops minus this diode. It is  $V_{CE}$ . So now,  $V_{CE}$  is maintained at assuming that all the diodes have same voltage drop when they are conducting. Now,  $V_{CE}$  is maintained at  $V_{BE}$  plus  $V_{D1}$ , voltage drop across 1 diode. Now, by connecting more number of diodes in this part, you can increase  $V_{CE}$ . I have just connected 2.

So, by connecting additional diodes in series with  $D_2$  or  $D_3$ ,  $V_{CE}$  can be increased. Now, how this network prevents transistor getting into saturation, this is one way of analyzing. How does this circuit work?

(Refer Slide Time: 46:31)

Assume Transistor is off.  
+ve  $I_B$  applied at point x  
Till  $V_{CE} = V_x - V_{D1}$   
 $D_1$  is off.  
All  $I_B$  will flow through  
 $D_2$  &  $D_3$  & into the base.

Assume that transistor is off, entire  $V_{CC}$  appears across the device and I want to turn on the transistor, as positive  $I_B$  is being applied to this circuit. See in this circuit, I have connected, I have used the Baker clamp, a transistor and there is a small load, a simple circuit to explain the principle. So, a positive  $I_B$  is applied at point x, this transistor is off, in other words, potential of C with respect to the ground is same as  $V_{CC}$ , there is no current here.

This is at  $V_x$ , definitely this voltage is very low. So,  $D_1$  is reverse biased, cathode potential is same as  $V_{CC}$  and anode potential is a potential of x and  $V_x$  is very small. So, all the current starts flowing through  $D_2$  and  $D_3$  and to the base. Transistor turns on, therefore,  $V_{CE}$  falls. Now, in order to reduce the  $t_{on}$ , I said that 1.5 times  $I_B$  should be supplied.

So,  $V_{CE}$  falls when this  $V_{CE}$  is equal to  $V_x$  minus  $V_{D1}$  or  $V_x$  minus 0.7 volts. I am assuming that voltage drop across  $D_1$  is 0.7. We will see what sort of diode is  $D_1$  and what could be the voltage drop across it, sometime later.

As of now, I will assume that voltage drop across  $D_1$  when it is conducting is 0.7 volts. So, when  $V_{CE}$  is  $V_x$  minus 0.7,  $D_1$  starts conducting. So, when  $D_1$  starts conducting, a part of  $I_B$  starts flowing through  $D_1$ , a part of  $I_B$  starts flowing there. So therefore, there is a reduction in current that is flowing into the base. I will repeat, initially  $D_1$  was off, transistor is off,  $V_{CE}$  or the collector potential is very high, may be is equal to  $V_{CC}$ . All the current flows through  $D_1$  and sorry, all the current flows through  $D_2$  and  $D_3$  and into the base.

As transistor turns on,  $V_{CE}$  falls and when  $V_{CE}$  is equal to  $V_x$  minus, this drop, voltage drop across  $D_1$ ,  $D_1$  turns on a part of the current starts flowing through diode  $D_1$  and this junction. So, there is going to be an automatic reduction of current flowing into  $D_2$  and  $D_3$ . Say second case, a

load has varied, see invariably, the base of circuit is designed in such a way that it supplies the required current for a full load and load or the load that the transistor was supplying is reduced. In other words,  $I_C$  has come down. Now, if I supply the same  $I_B$ , transistor will go into saturation. That is what I showed you, those 3 figures, active quasi saturation and saturation. As the charges are pumped into the base are increases,  $N_1$  layer reduces.

Now, the load has reduced. If I maintain the same  $I_B$ , transistor is entering into saturation,  $V_{CE}$  falls. But then  $V_{CE}$  in this circuit cannot fall below a value which is equal to  $V_X$  minus  $V_{D1}$ . See, in this circuit at any given time,  $V_{CE}$  is clamped at  $V_X$  minus  $V_{D1}$ . So, even the load has come down, if the load has come down, same  $I_B$  will not flow.

See, transistor is trying to get into go into saturation,  $V_C$  is trying to fall, the moment  $V_C$  is trying to fall,  $D_1$  turns on. It diverts some of the base current. So, base current gets diverted and therefore, this transistor cannot enter the saturation. So, that is all this Baker clamp works. Why do you require  $D_4$ ?  $D_4$  is to supply a negative  $I_B$ . Negative  $I_B$ ,  $D_1$  sorry,  $D_2$   $D_3$  for a positive  $I_B$  and  $D_4$  is for negative  $I_B$ .

All these current ratings,  $D_1$   $D_2$   $D_3$   $D_4$  current ratings are small, the maximum they carry, see this is a base drive current it has to carry but then voltage ratings of these diodes are different.  $D_2$   $D_3$   $D_4$  these are low voltage, low current diodes, whereas,  $D_1$  should be a high voltage diode. It should be a high voltage diode because when the transistor is off, cathode potential is at same, at  $V_{CC}$ .

So,  $D_1$  has to block the entire  $V_{CC}$ . So,  $D_1$  is a high voltage, low current diode, whereas these  $D_2$   $D_3$   $D_4$  are low voltage, low current diodes. So, with this I conclude my today's lecture.

Thank you.